IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant:

Kie Y. Ahn et al.

Title:

MULTILEVEL COPPER INTER

GAPS

Docket No.:

303.686US3

Filed:

February 25, 2004

Examiner:

Andy Huynh

Serial No.: 10/786,354 Due Date: January 15, 2005

SONNECTS WITH LOW-K DIELECTRICS AND AIR

Group Art Unit: 2818

Mail Stop Amendment

. Commissioner for Patents

- P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

 \underline{X} A return postcard.

X Amendment and Response Under 37 CFR 1.111 (8 Pages).

 \underline{X} Copy of pages 4 and 7 of Form 1449 originally submitted on February 25, 2004 (2 pgs.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

Atty: Timothy & Clise Reg. No. 40,957

<u>CERTIFICATE UNDER 37 CFR 1.8:</u> The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this <u>II</u> day of January, 2005.

FACIA

Name

Signature Loe

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)

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AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

This paper responds to the Office Action mailed on October 15, 2004. Please amend the above-identified patent application as follows.